

Title (en)

METHOD FOR PRODUCING STRUCTURED ELECTRICALLY CONDUCTIVE SURFACES

Title (de)

VERFAHREN ZUR HERSTELLUNG VON STRUKTURIERTEN, ELEKTRISCH LEITFÄHIGEN OBERFLÄCHEN

Title (fr)

PROCÉDÉ DE RÉALISATION DE SURFACES STRUCTURÉES CONDUCTRICES DE L'ÉLECTRICITÉ

Publication

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Application

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Abstract (en)

[origin: WO2008015201A1] The invention relates to a method for producing structured, and/or the entire surface spanning, electrically conductive surfaces (3, 11) on an electrically nonconductive carrier 5 (1), wherein in a first step the surfaces (3) of a first level are applied to the carrier (1), in a second step the insulating layer (9) is applied at those positions, at which structured, and/or the entire surface spanning, electrically conductive surfaces (11) of a second level cross the structured, and/or the entire surface spanning, electrically conductive surfaces (3) of the first level, and no electrical contact is to occur between the structured, and/or the entire surface spanning, electrically conductive surfaces of the first level (3) and of the second level (11), in a third step the structured, and/or the entire surface spanning, electrically conductive surfaces (11) of the second level are applied according the first step, and the second and third steps are repeated, if necessary.

IPC 8 full level

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